CY2DL1510 1:10 Differential LVDS Fanout Buffer

## Features

■ Low-voltage differential signal (LVDS) input with on-chip 100- $\Omega$ input termination resistor
■ Ten differential LVDS outputs
■ 40-ps maximum output-to-output skew
■ 600-ps maximum propagation delay
■ 0.11-ps maximum additive RMS phase jitter at 156.25 MHz (12-kHz to $20-\mathrm{MHz}$ offset)

■ Up to $1.5-\mathrm{GHz}$ operation

- Synchronous clock enable function
- 32-pin thin quad flat pack (TQFP) package

■ $2.5-\mathrm{V}$ or $3.3-\mathrm{V}$ operating voltage ${ }^{[1]}$
■ Commercial and industrial operating temperature range

## Functional Description

The CY2DL1510 is an ultra-low noise, low-skew, low-propagation delay 1:10 differential LVDS fanout buffer targeted to meet the requirements of high-speed clock distribution applications. The on-chip $100-\Omega$ input termination resistor reduces board component count, while the synchronous clock enable function ensures glitch-free output transitions during enable and disable periods. The device has a fully differential internal architecture that is optimized to achieve low-additive jitter and low-skew at operating frequencies of up to 1.5 GHz .

## Logic Block Diagram



Note

1. Input AC-coupling capacitors are required for voltage-translation applications.

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## Pinouts

Figure 1. Pin Diagram - CY2DL1510


Table 1. Pin Definitions

| Pin No. | Pin Name | Pin Type | Description |
| :--- | :--- | :--- | :--- |
| $1,9,16,25,32$ | $\mathrm{~V}_{\mathrm{DD}}$ | Power | Power supply |
| 2 | CLK_EN | Input | Synchronous clock enable. Low-voltage complementary metal oxide <br> semiconductor (LVCMOS)/low-voltage transistor-transistor-logic (LVTTL). <br> When CLK_EN = Low, Q(0:9) outputs are held low and Q(0:9)\# outputs are <br> held high |
| 3,4 | NC |  | No connection |
| 5 | $\mathrm{~V}_{\mathrm{BB}}$ | Output | LVDS reference voltage output |
| 6 | IN | Input | LVDS input clock |
| 7 | IN\# | Input | LVDS complementary input clock |
| 8 | $\mathrm{~V}_{\mathrm{SS}}$ | Power | Ground |
| $10,12,14,17,19,21$, <br> $23,26,28,30$ | $\mathrm{Q}(0: 9) \#$ | Output | LVDS complementary output clocks |
| $11,13,15,18,20,22$, <br> $24,27,29,31$ | $\mathrm{Q}(0: 9)$ | Output | LVDS output clocks |

## Absolute Maximum Ratings

| Parameter | Description | Condition | Min | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD}}$ | Supply voltage | Nonfunctional | -0.5 | 4.6 | V |
| $\mathrm{V}_{\text {IN }}{ }^{[2]}$ | Input voltage, relative to $\mathrm{V}_{\mathrm{SS}}$ | Nonfunctional | -0.5 | $\begin{aligned} & \text { lesser of } 4.0 \\ & \text { or } V_{D D}+0.4 \end{aligned}$ | V |
| $\mathrm{V}_{\text {OUT }}{ }^{[2]}$ | DC output or I/O Voltage, relative to $\mathrm{V}_{\text {SS }}$ | Nonfunctional | -0.5 | $\begin{aligned} & \text { lesser of } 4.0 \\ & \text { or } V_{D D}+0.4 \end{aligned}$ | V |
| $\mathrm{T}_{\text {S }}$ | Storage temperature | Nonfunctional | -55 | 150 | ${ }^{\circ} \mathrm{C}$ |
| ESD ${ }_{\text {HBM }}$ | Electrostatic discharge (ESD) protection (Human body model) | JEDEC STD 22-A114-B | 2000 | - | V |
| $\mathrm{L}_{U}$ | Latch up |  | Meets or exceeds JEDEC Spec JESD78B IC latch up test |  |  |
| UL-94 | Flammability rating | At 1/8 in. | V-0 |  |  |
| MSL | Moisture sensitivity level |  | 3 |  |  |

## Operating Conditions

| Parameter | Description | Condition | Min | Max | Unit |
| :--- | :--- | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD}}$ | Supply voltage | $2.5-\mathrm{V}$ supply | 2.375 | 2.625 | V |
|  |  | $3.3-\mathrm{V}$ supply | 3.135 | 3.465 | V |
| $\mathrm{~T}_{\mathrm{A}}$ | Ambient operating temperature | Commercial | 0 | 70 | ${ }^{\circ} \mathrm{C}$ |
|  | Industrial | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |  |
| $\mathrm{t}_{\text {PU }}$ | Power ramp time | Power-up time for $\mathrm{V}_{\mathrm{DD}}$ to reach <br> minimum specified voltage (power <br> ramp must be monotonic.) | 0.05 | 500 | ms |
|  |  |  |  |  |  |

Note
2. The voltage on any I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.

## DC Electrical Specifications

$\left(\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V} \pm 5 \%\right.$ or $2.5 \mathrm{~V} \pm 5 \%$; $\mathrm{T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ (Commercial) or $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ (Industrial))

| Parameter | Description | Condition | Min | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{I}_{\mathrm{DD}}$ | Operating supply current | All LVDS outputs terminated with $100 \Omega$ load ${ }^{[3,4]}$ | - | 125 | mA |
| $\mathrm{V}_{\mathrm{IH} 1}$ | Input high Voltage, LVDS input clocks, IN and IN\# |  | - | $\mathrm{V}_{\mathrm{DD}}+0.3$ | V |
| $\mathrm{V}_{\text {IL1 }}$ | Input low voltage, LVDS input clocks, IN and IN\# |  | -0.3 | - | V |
| $\mathrm{V}_{\mathrm{IH} 2}$ | Input high voltage, CLK_EN | $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}$ | 2.0 | $\mathrm{V}_{\mathrm{DD}}+0.3$ | V |
| $\mathrm{V}_{\text {IL2 }}$ | Input low voltage, CLK_EN | $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}$ | -0.3 | 0.8 | V |
| $\mathrm{V}_{\mathrm{IH} 3}$ | Input high voltage, CLK_EN | $\mathrm{V}_{\mathrm{DD}}=2.5 \mathrm{~V}$ | 1.7 | $\mathrm{V}_{\mathrm{DD}}+0.3$ | V |
| $\mathrm{V}_{\text {IL3 }}$ | Input low voltage, CLK_EN | $\mathrm{V}_{\mathrm{DD}}=2.5 \mathrm{~V}$ | -0.3 | 0.7 | V |
| $\mathrm{V}_{1 \mathrm{D}}{ }^{[5]}$ | Input differential amplitude | See Figure 3 on page 7 | 0.4 | 0.8 | V |
| $V_{\text {ICM }}$ | Input common mode voltage | See Figure 3 on page 7 | 0.5 | $\mathrm{V}_{\mathrm{DD}}-0.2$ | V |
| $\mathrm{I}_{\mathrm{IH}}$ | Input high current, All inputs | Input $=\mathrm{V}_{\mathrm{DD}}{ }^{[6]}$ | - | 150 | $\mu \mathrm{A}$ |
| IIL | Input low current, All inputs | Input $=\mathrm{V}_{\text {SS }}{ }^{[6]}$ | -150 | - | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\mathrm{PP}}$ | LVDS differential output voltage peak to peak, single-ended | $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}$ or 2.5 V , <br> $R_{\text {TERM }}=100 \Omega$ between $Q$ and $Q \#$ pairs ${ }^{[3,7]}$ | 250 | 470 | mV |
| $\Delta \mathrm{V}_{\text {OCM }}$ | Change in $\mathrm{V}_{\text {OCM }}$ between complementary output states | $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}$ or 2.5 V , <br> $\mathrm{R}_{\text {TERM }}=100 \Omega$ between Q and $\mathrm{Q} \#$ pairs ${ }^{[3,7]}$ | - | 50 | mV |
| $\mathrm{V}_{\mathrm{BB}}$ | Output reference voltage | 0 to $150 \mu \mathrm{~A}$ output current | 1.125 | 1.375 | V |
| $\mathrm{R}_{\text {TERM }}$ | On-chip differential input termination resistor |  | 80 | 120 | $\Omega$ |
| $\mathrm{R}_{\mathrm{P}}$ | Internal pull-up resistance, LVCMOS logic input | CLK_EN pin | 60 | 140 | k $\Omega$ |
| $\mathrm{C}_{\text {IN }}$ | Input capacitance | Measured at 10 MHz per pin | - | 3 | pF |

## Notes

3. Refer to Figure 2 on page 7 .
4. $I_{D D}$ includes current that is dissipated externally in the output termination resistors.
5. $\mathrm{V}_{I D}$ minimum of 400 mV is required to meet all output $A C$ Electrical Specifications. The device is functional with $\mathrm{V}_{I D}$ minimum of greater than 200 mV .
6. Positive current flows into the input pin, negative current flows out of the input pin.
7. Refer to Figure 4 on page 7.

## AC Electrical Specifications

( $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V} \pm 5 \%$ or $2.5 \mathrm{~V} \pm 5 \%$; $\mathrm{T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ (Commercial) or $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ (Industrial))

| Parameter | Description | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{F}_{\text {IN }}$ | Input frequency |  | DC | - | 1.5 | GHz |
| Fout | Output frequency | $\mathrm{F}_{\text {OUT }}=\mathrm{F}_{\text {IN }}$ | DC | - | 1.5 | GHz |
| $\mathrm{t}_{\text {PD }}{ }^{[10]}$ | Propagation delay input pair to output pair | Input rise/fall time < 1.5 ns (20\% to 80\%) | - | - | 600 | ps |
| $\mathrm{t}_{\mathrm{ODC}}{ }^{[11]}$ | Output duty cycle | 50\% duty cycle at input Frequency range up to 1 GHz | 48 | - | 52 | \% |
| $\mathrm{t}_{\text {SK1 }}{ }^{\text {[12] }}$ | Output-to-output skew | Any output to any output, with same load conditions at DUT | - | - | 40 | ps |
| $\mathrm{t}_{\text {SK1 D }}{ }^{\text {[12] }}$ | Device-to-device output skew | Any output to any output between two or more devices. Devices must have the same input and have the same output load. | - | - | 150 | ps |
| PN ${ }_{\text {ADD }}$ | Additive RMS phase noise <br> $156.25-\mathrm{MHz}$ input <br> Rise/fall time < 150 ps (20\% to 80\%) $\mathrm{V}_{\mathrm{ID}}>400 \mathrm{mV}$ | Offset $=1 \mathrm{kHz}$ | - | - | -120 | $\mathrm{dBc} / \mathrm{Hz}$ |
|  |  | Offset $=10 \mathrm{kHz}$ | - | - | -135 | $\mathrm{dBc} / \mathrm{Hz}$ |
|  |  | Offset $=100 \mathrm{kHz}$ | - | - | -135 | $\mathrm{dBc} / \mathrm{Hz}$ |
|  |  | Offset $=1 \mathrm{MHz}$ | - | - | -150 | $\mathrm{dBc} / \mathrm{Hz}$ |
|  |  | Offset $=10 \mathrm{MHz}$ | - | - | -154 | $\mathrm{dBc} / \mathrm{Hz}$ |
|  |  | Offset $=20 \mathrm{MHz}$ | - | - | -155 | $\mathrm{dBc} / \mathrm{Hz}$ |
| $\mathrm{t}_{\mathrm{JIT}}{ }^{[13]}$ | Additive RMS phase jitter (Random) | 156.25 MHz, 12 kHz to 20 MHz offset; input rise/fall time < 150 ps (20\% to 80\%), $\mathrm{V}_{\mathrm{ID}}>400 \mathrm{mV}$ | - | - | 0.11 | ps |
| $\mathrm{t}_{\mathrm{R}}, \mathrm{t}_{\mathrm{F}}{ }^{[14]}$ | Output rise/fall time, single-ended | 50\% duty cycle at input, $20 \%$ to $80 \%$ of full swing $\left(\mathrm{V}_{\mathrm{OL}}\right.$ to $\left.\mathrm{V}_{\mathrm{OH}}\right)$ Input rise/fall time < 1.5 ns (20\% to 80\%) <br> Measured at 1 GHz | - | - | 300 | ps |
| ${ }^{\text {tSOD }}$ | Time from clock edge to outputs disabled | Synchronous clock enable (CLK_EN) switched low | - | - | 700 | ps |
| $\mathrm{t}_{\text {SOE }}$ | Time from clock edge to outputs enabled | Synchronous clock enable (CLK_EN) switched high | - | - | 700 | ps |

## Notes

8. Refer to Figure 2 on page 7.
9. Refer to Figure 4 on page 7.
10. Refer to Figure 5 on page 7.
11. Refer to Figure 6 on page 7.
12. Refer to Figure 7 on page 8.
13. Refer to Figure 8 on page 8.
14. Refer to Figure 9 on page 8.

Figure 2. LVDS Output Termination


Figure 3. Input Differential and Common Mode Voltages


Figure 4. Output Differential and Common Mode Voltages


Figure 5. Input to Any Output Pair Propagation Delay


Figure 6. Output Duty Cycle


Figure 7. Output-to-output and Device-to-device Skew


Figure 8. RMS Phase Jitter


Figure 9. Output Rise/Fall Time


Figure 10. Synchronous Clock Enable Timing


## Ordering Information

| Part Number | Type | Production Flow |
| :--- | :--- | :--- |
| Pb-free | 32-Pin TQFP | Commercial, $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ |
| CY2DL1510AZC | 32-Pin TQFP tape and reel | Commercial, $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ |
| CY2DL1510AZCT | 32-Pin TQFP | Industrial, $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ |
| CY2DL1510AZI | 32-Pin TQFP tape and reel | Industrial, $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ |
| CY2DL1510AZIT |  |  |

## Ordering Code Definition



## Package Dimension

Figure 11. 32-Pin Thin Plastic Quad Flat Pack $7 \times 7 \times 1.0 \mathrm{~mm}$


## Acronyms

Table 2. Acronyms Used in this Document

| Acronym | Description |
| :--- | :--- |
| ESD | electrostatic discharge |
| HBM | human body model |
| JEDEC | Joint electron devices engineering council |
| LVDS | low-voltage differential signal |
| LVCMOS | low-voltage complementary metal oxide <br> semiconductor |
| LVTTL | low-voltage transistor-transistor logic |
| OE | Output enable |
| RMS | root mean square |
| TQFP | thin quad flat pack |

Document Conventions
Table 3. Units of Measure

| Symbol | Unit of Measure |
| :--- | :--- |
| ${ }^{\circ} \mathrm{C}$ | degree Celsius |
| dBc | decibels relative to the carrier |
| GHz | giga hertz |
| Hz | hertz |
| $\mathrm{k} \Omega$ | kilo ohm |
| $\mu \mathrm{A}$ | microamperes |
| $\mu \mathrm{F}$ | micro Farad |
| $\mu \mathrm{s}$ | micro second |
| mA | milliamperes |
| ms | millisecond |
| mV | millivolt |
| MHz | megahertz |
| ns | nanosecond |
| $\Omega$ | ohm |
| pF | pico Farad |
| ps | pico second |
| V | volts |
| W | watts |

## Document History Page

Document Title: CY2DL1510 1:10 Differential LVDS Fanout Buffer
Document Number: 001-54863

| Revision | ECN | Orig. of Change | Submission Date | Description of Change |
| :---: | :---: | :---: | :---: | :---: |
| ** | 2744225 | CXQ/PYRS | 08/19/09 | New datasheet. |
| *A | 2782891 | CXQ | 10/09/09 | Updated format of Logic Block Diagram on page 1. <br> Added $\mathrm{T}_{\text {SOD }}$ and $\mathrm{T}_{\text {SOE }}$ specs ( 700 ps max) to AC Specs table. Added $\mathrm{T}_{\text {SETUP }}$ and $\mathrm{T}_{\text {HOLD }}$ specs ( 300 ps min ) to AC Specs table. Changed equation for RMS jitter in Figure 8 to proportionality. Changed package drawing from 1.4 mm thickness $51-85088 \mathrm{spec}$ to 1.0 mm thickness $51-850063 \mathrm{spec}$. <br> Added "Synchronous Clock Enable Function" to Features on page 1. |
| *B | 2838916 | CXQ | 01/05/2010 | Changed status from "ADVANCE" to "PRELIMINARY". <br> Changed from 0.34 ps to 0.25 ps maximum additive jitter in "Features" on page 1 and in $\mathrm{t}_{\text {JIT }}$ in the AC Electrical Specs table on page 5 . <br> Added $\mathrm{t}_{\mathrm{PU}} \mathrm{spec}$ to the Operating Conditions table on page 3. <br> Removed $\mathrm{V}_{\mathrm{OD}}$ and $\Delta \mathrm{V}_{\mathrm{OD}}$ specs from the DC Electrical Specs table on page 4. <br> Added $\mathrm{V}_{\mathrm{PP}}$ and $\Delta \mathrm{V}_{\mathrm{PP}}$ specs to the AC Electrical Specs table on page 5. $\mathrm{V}_{\mathrm{PP}} \min =250 \mathrm{mV}$ and $\max =470 \mathrm{mV} ; \Delta \mathrm{V}_{\mathrm{PP}} \max =50 \mathrm{mV}$. <br> Added internal pullup resistance spec for CLK_EN in the DC Electrical Specs table on page 4. $\operatorname{Min}=60 \mathrm{k} \Omega, \mathrm{Max}=1 \overline{40} \mathrm{k} \Omega$. <br> Added a measurement definition for $\mathrm{C}_{\mathrm{IN}}$ in the DC Electrical Specs table on page 4. <br> Changed letter case and some names of all the timing parameters in the AC Electrical Specs table on page 5 to be consistent with EROS. <br> Lowered all additive phase noise mask specs by 3 dB in the AC Electrical Specs table on page 5 . <br> Added condition to $t_{R}$ and $t_{F}$ specs in the AC Electrical specs table on page 5 that input rise/fall time must be less than 1.5 ns ( $20 \%$ to $80 \%$ ). Changed letter case and some names of all the timing parameters in Figures 5, 6, 7, and 9, to be consistent with EROS. Updated Figure 4 with definitions for $V_{P P}$ and $\Delta V_{P P}$. |
| *C | 2885033 | CXQ | 02/26/2010 | Updated 32-Pin TQFP package diagram. |
| *D | 3011766 | CXQ | 08/20/2010 | Changed maximum additive jitter from 0.25 ps to 0.11 ps in "Features" on page 1 and in $t_{J I T}$ in the AC Electrical Specs table on page 5 . Changed max $\mathrm{t}_{\mathrm{PD}}$ spec from 480 ps to 600 ps . Added note 5 to describe $\mathrm{I}_{\mathrm{IH}}$ and $\mathrm{I}_{\mathrm{IL}}$ specs. <br> Removed reference to data distribution from "Functional Description". Changed $R_{P}$ for differential inputs from $100 \mathrm{k} \Omega$ to $150 \mathrm{k} \Omega$ in the Logic Block Diagram and from $60 \mathrm{k} \Omega \mathrm{min} / 140 \mathrm{k} \Omega \max$ to $90 \mathrm{k} \Omega \min / 210 \mathrm{k} \Omega$ max in the DC Electrical Specs table. <br> Added $\mathrm{V}_{\text {ID }}$ max spec of 0.8 V in the DC Electrical Specs table. Updated phase noise specs for $1 \mathrm{k} / 10 \mathrm{k} / 100 \mathrm{k} / 1 \mathrm{M} / 10 \mathrm{M} / 20 \mathrm{MHz}$ offset to $-120 /-130 /-135 /-150 /-150 /-150 \mathrm{dBc} / \mathrm{Hz}$, respectively, in the AC Electrical Specs table. <br> Added "Frequency range up to 1 GHz " condition to $\mathrm{t}_{\mathrm{ODC}}$ spec. Added Acronyms and Ordering Code Definition. |
| *E | 3017258 | CXQ | 08/27/2010 | Corrected Output Rise/Fall time diagram. |

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 Document Number: 001-54863| Revision | ECN | Orig. of Change | Submission Date | Description of Change |
| :---: | :---: | :---: | :---: | :---: |
| *F | 3100234 | CXQ | 11/18/2010 | Changed $\mathrm{V}_{\text {IN }}$ and $\mathrm{V}_{\text {OUT }}$ specs from 4.0 V to "lesser of 4.0 or $\mathrm{V}_{\mathrm{DD}}+0.4$ " Removed 200mA min LU spec, replaced with "Meets or exceeds JEDEC Spec JESD78B IC Latchup Test" <br> Moved $\mathrm{V}_{\mathrm{PP}}$ from AC spec table to DC spec table, removed $\Delta \mathrm{V}_{\mathrm{PP}}$. Removed $\mathrm{R}_{\mathrm{P}}$ spec for differential input clock pins $\mathrm{IN} \mathrm{N}_{\mathrm{X}}$ and $\mathrm{I} \mathrm{N}_{\mathrm{X}} \#$. Changed $\mathrm{C}_{\mathrm{IN}}$ condition to "Measured at 10 MHz ". <br> Changed $\mathrm{PN}_{\text {ADD }}$ specs for $10 \mathrm{kHz}, 10 \mathrm{MHz}$, and 20 MHz offsets. <br> Added "Measured at 1 GHz " to $\mathrm{t}_{\mathrm{R}}, \mathrm{t}_{\mathrm{F}} \mathrm{spec}$ condition. <br> Removed $t_{S}$ and $t_{H}$ specs from AC specs table. <br> Changed to CY2DL1510AZ package code in Ordering Information. Added to $Z$ package code in Ordering Code Definition. |
| *G | 3135201 | CXQ | 01/12/2011 | Removed "Preliminary" status heading. <br> Fixed typo and removed resistors from IN/IN\# in Logic Block Diagram. Added Figure 10 to describe $\mathrm{T}_{\text {SOE }}$ and $\mathrm{T}_{\text {SOD }}$. |
| *H | 3090938 | CXQ | 02/25/2011 | Post to external web. |

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